06-Oct	Professional Development Courses			(	07-Oct					
09:00		registration		C	08:00		registration			
10:00	PDC 1	ESA	Working with ESA: EEE sovereignty, qualification, technology development funding	C	09:00		_	ESA	Welcome	
11:00		break		C	09:10		welcome	Global Electronics Association	The path towards Advanced Electronic Packaging	
11:30	PDC 2	placeholder	Advanced packaging	C	09:20	1		Advanced Technology Institute, University Of Surrey, Jose Anguita	Compact System for Printing Electronics with Potential for Space Applications	
13:00		lunch		C	09:45	2	additive manufactured	Politecnico di Milano, Andrea Mistrini	Laser Additive Manufacturing of High-Performance Thermal Management Systems for Aerospace High-Power Electronics	
14:00	PDC 3	Spacechips, Rajan Bedi	Flexible PCB Design and Manufacturing for Space Applications	1	10:10	3	electronics	Holst Centre - Tno, Darragh Walsh	Novel Additive Manufacturing Platform for Freeform 3D Microelectronics and Packaging	
15:00		break		1	10:35	4		Jadavpur University, Soham Ghosh	Design of Scalp-Implantable and Non-Invasive Antenna System for Intracranial Pressure Monitoring	
15:20	PDC 4	Spacechips, Rajan Bedi	Right-First-Time Design for Fabrication and Assembly Considerations When Manufacturing Space-Grade PCBs	1	11:00		break			
16:20		break		1	11:30	5		Alter Technology, Mari Carmen López	Critical Role of Tg and CTE Characterization in PCB Design Using Thermomechanical Analys (TMA)	
16:40	PDC 5	ESA	Space mission classification and the materials & processes control board	1	11:55	6	PCB 1	Hytek, Poul Juul	Physical characterization of PCB materials	
17:40		end		1	12:20	7		Istituto Italiano Della Saldatura, Luca Moliterni	Study of Base Laminates Used for High Reliability Printed Circuits Boards	
				1	12:45	8		LPKF Laser & Electronics, Patrick Stockbrügger	Potential of laser depaneling for harsh environments in terms of quality and reliability	
				1	13:10		lunch			
				1	14:10	9		Nanospace, Pascale Wiesmann	Lead-free assembly technologies for telecom satellite equipment (ESA ARTES)	
				1	14:35	10	lead-free assembly	Technical University of Darmstadt, Guillaume Meyer	Lead-Free Transition for the European Space Sector - the Tin Whiskers Challenge	
				1	15:00	11		Spur Electron, Cathy Chandler	Lead-free assembly technologies for telecom satellite equipment	
7, 8 Oct	Poster presentations during afternoon breaks			1	15:25	12		Teledyne E2v, Eric Perriaud	Board Level Reliability Testing of BGA Packages Equipped with Lead-Free Interconnection Solutions and Dedicated to Space Applications	
	46 Sapienza University Of Rome, Simone Bandini		Morphological and Compositional Evolution of InPb/Au Solder Joints under Thermal Ageing in Atmospheric and Vacuum Environments	1	15:50		break		Poster presentations	
	47	Manchester Metropolitan University, Sunday Enahoro	Digital Twin-Enabled Design and Sustainability Assessment of mmWave Energy Harvesting Antennas for Satellite and IoT Applications	1	16:20	13 14	modelling	Hooke Electronics, Jean-Baptiste Libot	Physics-of-Failure Based Reliability Modeling of Lead-Free Electronic Assemblies Under Thermal Cycling	
	48	HTV Conservation GmbH, Thorsten Leist	Quality assurance of additively manufactured electronics	1	16:45			Schaeffler, Nicolae Badulescu	Approach for Coupled Simulations of Magnetic Power Loss and Temperature Distribution of DC/DC Converter Used for Electric Vehicles	
	49	DSI Aerospace, Jan Frederik Wagenfeld	PCB Design Challenges in Next-Generation Space Mass Memory Units	1	17:10	15		Imec, Klara Volckaert	Experimental Data-Driven Prediction of Input Parameters for Finite Element Simulations for Electronic Assemblies	
				1	17:35		end			
				1	18:00		welcome reception at Space EXPO			
				2	20:00		end			

08-Oct					09-Oct				
09:00	16	_	Thales Alenia Space, Paula Marin Banque	Low loss PCB solutions - focus on nickel-free finishes Novel Surface Finish for High frequency PCB Technologies- How to Achieve Optimum Signal Integrity & Reliability.	09:00	33	33 34	Istituto Italiano Della Saldatura, Luca Moliterni	The Surface Insulation Resistance (SIR) test according to ECSS-Q-ST-70-61 and IPC-TM-650 2.6.3.7 for flux residues study
09:25	17	_	LILOTREE, Kunal Shah		09:25	34		PBT Works, Vladimir Sítko	Cleaning of electronic assembly: development and qualification using the Glass Test board
09:50	18	assembly	Thales Alenia Space Italia, Andres Matias Dabas	Qualification of high-speed press-fit connectors for space applications	09:50	35	assembly a modelling	Elemca, Jeremie Dhennin	Finite Element Modeling of SAC305 Solder Joint Reliability under Thermomechanical Cycling for Space Applications
10:15	19	_	Thales Alenia Space, Hugo Garcia	Evaluation of Pressfit Technology for High-Reliability Space Applications	10:15	36		Thales Alenia Space Belgium, Vincent Voet	Thermomechanical fatigue lifetime prediction of solder joints in electronic component assemblies
10:40	20		OHB System, Alexander Hannes	Microcoil Springs – an alternative to CCGA tin columns	10:40		break		
11:05		break			11:10	37	_	AEMtec, Robin Jerratsch	Status on GSTP "Definition and validation of an European source of FC Bump services for 28nm and lower technology nodes"
11:35	21	-	Ncab Group, Jan Pedersen	The PCB Journey from Multilayer to Ultra HDI	11:35	38	EEE packaging 2	Tno Defence, Safety And Security, Victoria Gomez-guillamon Buendia	Advanced packaging technologies for next generation integrated RF systems
12:00	22		Alter Technology, Mari Carmen López	High Temperature Lead Free Solder for Internal Soldering of EEE Parts: Manufacturing and Testing	12:00	39		Thales Alenia Space Italia, Andres Matias Dabas	Advanced Digital Processor System-in-Package (SiP) for space applications
12:25	23		Alter Technology, Luis Alejandro Arriaga Arellano	Space Radiation shielding in microelectronics through the development of advanced composite Materials (SRPROTEC Project)	12:25	40		Thales Alenia Space Italia, Mirko Rocci	Advanced uHDI and Embedded-Power SiP Technology for Space Applications
12:50	24		Ghent University / Imec, Geert Van Steenberge	Wafer-Scale Packaging of Photonic Switches and Transceivers	12:50	41		Fraunhofer Izm, Tekfouy Lim	Advanced system integration technologies for Space applications
13:15		lunch			13:15		lunch		
14:15	25	_	ACB, Joachim Verhegge	High-speed HDI technology for space applications: a road to qualification	14:15	42		ESA, Jordi Oller Sánchez	CT Scan as a Non-Destructive Alternative to Microsectioning for Electronic Assembly Verification
14:40	26		Oki Circuit Technology, Ogura Toshihiko	Development of HDI PCBs using low-loss materials	14:40	43	- assembly testing	Jtag Technologies, Peter van den Eijnden	TapSpacer: remote access to embedded JTAG boundary-scan logic
15:05	27		Cistelaier, Gianluca Parodi	Approaching New Challenges: How We Got to Space"	15:05	44	1	Airbus Defence And Space, Asensio Zapata	Asymmetric test cycling as a new approach for validation of electronic assemblies in harsh environment
15:30	28		llfa Gmbh, Athanasios Kallinis	Copper-Based Sinter Paste Integration for Advanced PCB Packaging and Multiboard Architectures	15:30	45		Thales Alenia Space Italy, Luca Tomarchio	Limits and Requirements for the Qualification of spaceborne Rydberg Quantum sensors
15:55		break		Poster presentations	15:55		closing	ESA, Global Electronics Association	
16:25	29	-	Elemca, Jeremie Dhennin	EBSD Evaluation of the Impact of Reflow Temperature on Microvia Microstructure	16:05		end		
16:50	30	- PCB & modelling	Imec, Maarten Cauwe	Microvia manufacturing capability assessment: a perspective on three levels of stacked microvias					
17:15	31		Imec, Chinmay Nawghane	Optimizing Multilevel Microvia Structures for Thermo-Mechanical Reliability in High-Speed HDI PCBs					
17:40	32		Elastic-Simulations Gmbh, Harald Ziegelwanger	Modelling the reliability of through-hole-technology assemblies					
18:05		end							
20:00	0 dinner on Noordwijk beach								
23:30		end							